

AW-PU551

NXP i.MX 8M Nano SoM with Wi-Fi 1x1 Connectivity

Datasheet

Rev. F

DF

(For Standard)

Features

Arm Cortex-A53 MPCore platform

- Quad symmetric Cortex®-A53 processors
- 32 KB L1 Instruction Cache
- 32 KB L1 Data Cache
- Media Processing Engine (MPE) with Arm® NEON™ technology supporting the Advanced Single Instruction Multiple Data architecture.
- Floating Point Unit (FPU) with support of the Arm® VFPv4-D16 architecture
- Support of 64-bit Arm®v8-A architecture
- 512 KB unified L2 cache

Arm Cortex-M7 core platform

- Low power standby mode
- IoT features including Weave
- Manage IR or Wireless Remote
- ML inference applications (Enhanced for AW-PU551)
- 32 KB L1 Instruction Cache
- 32 KB L1 Data Cache
- 256 KB tightly coupled memory (TCM)

Graphic Processing Unit

- GC7000UL with OpenCL and Vulkan support
- 2 shader
- 99.8 million triangles/sec
- 0.6 giga pixel/sec
- 9.6 GFLOPs 32-bit/19.2 GFLOPs 16-bit
- Supports OpenGL ES 1.1, 2.0, 3.0, OpenCL
- Core clock frequency of 600 MHz
- Shader clock frequency of 600 MHz

LCDIF Display Controller

- Support up to 1080p60 display through MIPI DSI

Audio

- S/PDIF input and output, including a raw Capture input mode
- Five synchronous audio interface (SAI) modules supporting I2S, AC97, TDM, codec/DSP, and DSD interfaces.
- One SAI with 4 Tx and 4 Rx lanes, two SAI with 2 Tx and 2 Rx lanes, and two SAI with 1 Tx and 1 Rx lanes.
- ASRC supports processing 32 audio channels, 4 context groups, 8 kHz to 384 kHz sample rate and 1/16 to 8x sample rate conversion ratio.
- Pulse Density Modulation (PDM) input

Connectivity

- One USB 2.0 OTG controllers with integrated PHY interface.(Spread spectrum clock support)
- One Ultra Secure Digital Host Controller (uSDHC) interface. SD/SDIO 3.0 compliance with 200 MHz SDR signaling to support up to 100MB/sec. Also support for SDXC (extended capacity)
- One Gigabit Ethernet controller with support for Energy Efficient Ethernet (EEE), Ethernet AVB, and IEEE 1588.
- Two Universal Asynchronous Receiver/Transmitter (UART) modules.
- Three I2C modules.
- One ECSPi modules

On board memory

- Ram : 512MB(4Gb) 16bit DDR3L-1600.
- Flash : 8GB(64Gb) eMMC 5.1 / 16GB(128Gb) eMMC 5.1 (Option)

MIPI Interface

- 4-lane MIPI DSI interface
- 4-lane MIPI CSI interface

WLAN

- 1 antennas to support 1(Transmit) x 1(Receive) technology and Bluetooth
- High speed wireless connection up to 433.3Mbps transmit/receive PHY rate using 80MHz bandwidth
- Backward compatibility with legacy 802.11n/a/g/b technology.
- 20MHz bandwidth/ channel, 40MHz bandwidth/ channel, upper/ lower 20MHz packets in 40MHz channel, 20MHz duplicate legacy packets in 40MHz channel mode operation.
- 80MHz bandwidth/ channel, 4 positions of 20MHz packets in 80MHz channel, upper/ lower 40MHz packets in 80MHz channel, 20MHz quadruplicate legacy packets in 80MHz channel mode operation.
- Dynamic frequency selection (radar detection)
- Enhanced radar detection for long and short pulse radar
- Enhanced AGC scheme for DFS channel.
- 20/40/80Mhz coexistence with middle packet detection (GI detection) for enhanced CCA.
- 1 spatial stream STBC reception.
- LDPC transmission and reception for both 802.11n/a/g/b MCS 8, 9 modulation, optional support for 802.11ac MCS 9 in 20MHz using LDPC.
- Short guard interval.
- Temporal Key Integrity Protocol (TKIP)/ Wired Equivalent Privacy (WEP)/ Advanced Encryption Standard (AES)/ Counter Mode/ CBC MAC Protocol (CCMP)
- Infrastructure (WAPI).1n and 802.11ac.

WLAN

- Cipher Based Message Authentication Code (CMAC)/ WLAN Authentication and Privacy

Bluetooth

- Baseband and radio BDR and EDR packet types 1Mbps (GFSK), 2Mbps (π/4 DQPSK), and 3Mbps (8DPSK).
- Bluetooth 5.2 support.
- Enhanced Data Rate (EDR) compliant for both 2Mbps and 3Mbps supported.
- High speed UART and PCM for Bluetooth.
- Fully functional Bluetooth baseband AFH, forward error correction, header error control, access code correlation, CRC, encryption bit stream generation, and whitening.
- Adaptive Frequency Hopping (AFH) using Packet Error Rate (PER).
- SCO/ eSCO links with hardware accelerated audio signal processing and hardware supported PPEC algorithm for speech quality improvement.
- Standard Bluetooth power saving mechanisms.
- Automatic ACL packet type selection.
- Full master and slave piconet support.
- Scatternet support.
- Enhanced Power Control (EPC).
- Channel Quality Driven Data Rate (CQDDR).
- Encryption (AES) support.
- Supports link layer topology to be master and slave (connects up to 16 links).
- LE Privacy 1.2
- LE Secure Connection.
- LE Data Length Extension.
- 2 Mbps LE
- Direction Finding – Connectionless Angle of Departure (AoD).
- Direction Finding – Connection – oriented Angle of Arrival (AoA)

Revision History

Document NO: R2-3551-DST-01

Version	Revision Date	DCN NO.	Description	Initials	Approved
A	2019/10/08		<ul style="list-style-type: none"> Initial Version 	Licheng Wang	Chihhao Liao
B	2020/07/14	DCN016993	<ul style="list-style-type: none"> Modify Ordering information Ram size from 1GB to 512MB. Modify 1.3.4 Operating temperature. Modify 2.2 Pin Table <ol style="list-style-type: none"> Pin2 and pin4 description. Pin26 and Pin27 description. Add 5 Packaging Information 	Licheng Wang	Chihhao Liao
C	2020/11/27	DCN018880	<ul style="list-style-type: none"> Update 1.2.2 Ordering information Modify 1.3.1 General's dimension height. Modify 1.3.1 General's major chipset description. Modify ENET voltage level from 2.5V to NCVV_ENET in 2.2 pin table. Add NVCC_ENET description in 3.2 Recommended Operating Conditions. Modify 4.1 Mechanical Drawing. Add warpage spec. 	Licheng Wang	Chihhao Liao
D	2021/04/29	DCN021634	<ul style="list-style-type: none"> Update Azurewave Format Update Pin Table to top view. Update ESD protection description. Update Product Description. 	Licheng Wang	Chihhao Liao
E	2021/06/29	DCN026792	<ul style="list-style-type: none"> Update BT to BT5.2. Modify chapter 1.3.1 description. Modify pin 60 I/O as 1.8V. Modify 2.2 Pin Table SD2 to 1.8V/3.3V. Update 3.6 Power consumption. 	Licheng Wang	Chihhao Liao
F	2023/12/27	DCN030800	<ul style="list-style-type: none"> Update eMMC capacity to 8GB (default) and ordering information 	Licheng Wang	Renton Tao

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1. Introduction

1.1 Product Overview

AzureWave Technologies, Inc. introduces the NXP i.MX 8M Nano SoM with Wi-Fi 1x1 Connectivity --- **AW-PU551**. AW-PU551 is an advanced application processor designed for smart audio and smart home applications. It integrates a powerful CPU subsystem, advanced multi-format audio processing unit, a secured runtime environment and all major peripherals for versatile smart home applications.

The main system CPU is a quad-core ARM Cortex-A53 CPU with 32 KB L1 Instruction Cache and a 512KB unified L2 cache to improve system performance. Cortex-A53 CPU can run up to 1.5GHz.

Media Processing Engine (MPE) with Arm NEON technology supporting the Advanced Single Instruction Multiple Data architecture. Floating Point Unit (FPU) with support of the Arm VFPv4-D16 architecture. Also support of 64-bit Arm@v8-A architecture.

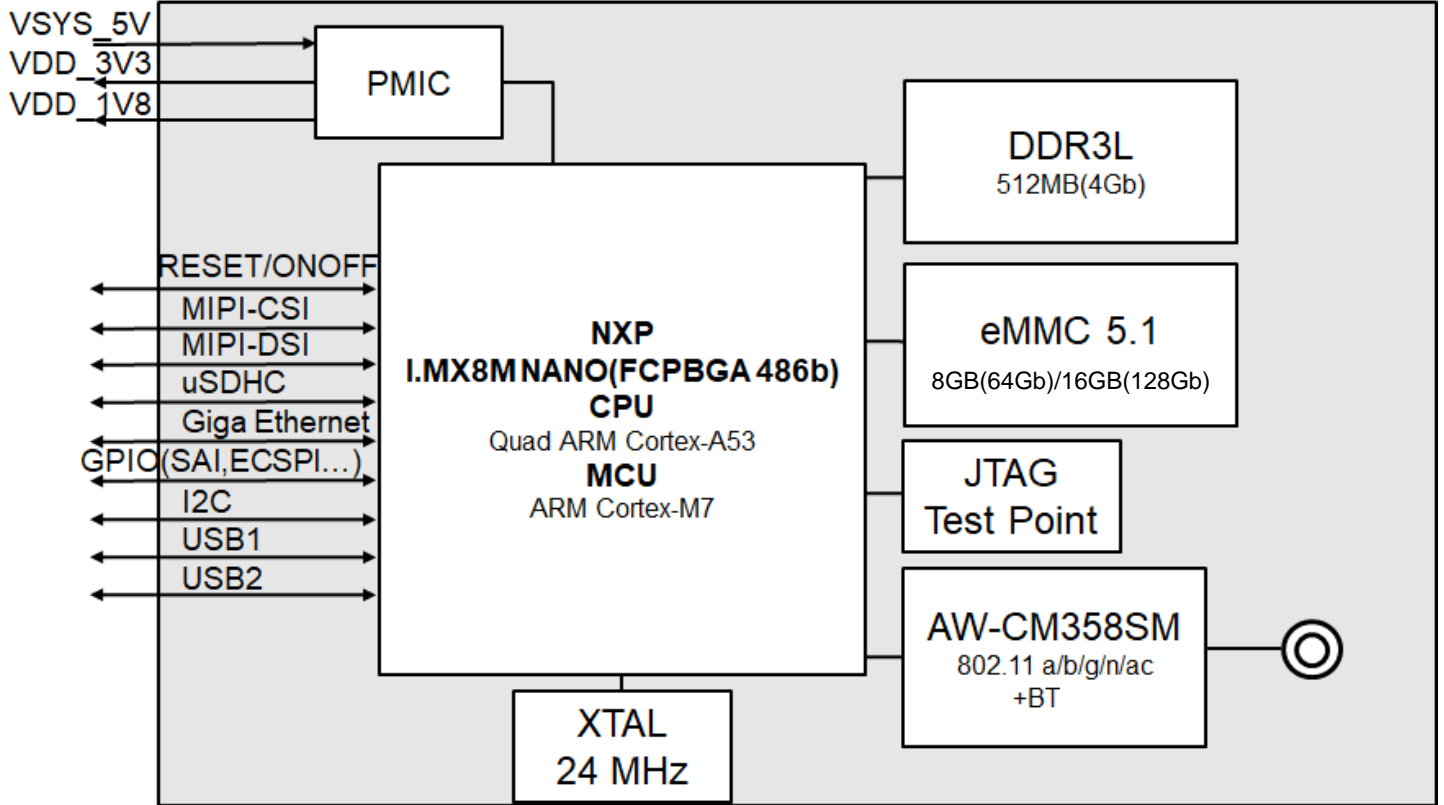
AW-PU551 integrates a wide range of standard audio input/output interfaces including multiple TDM, AC97, I2S and SPDIF. And Pulse Density Modulation (PDM) input. AW-PU551 module supports IEEE 802.11 a/b/g/n/ac 2.4GHz and 5GHz. It's also support BT5.2 with EDR and BLE. It has rich advanced peripheral interfaces, including USB 2.0 high-speed OTG port, SDIO controllers, UARTs, I2Cs, and PWMs.

The IMX8M Nano SoC enabling application headroom for OEM features applications. The quad-core ARM Cortex-A53 architecture also supports advanced DSP algorithms for audio echo cancellation, beamforming, noise reduction, as well as audio post-processing, which eliminates the need for DSP hardware.

AW-PU551 module adopts NXP latest highly-integrated dual-band WLAN & Bluetooth SoC--- **88W8987**. All the other components are implemented by all means to reach the mechanical specification required.

1.2 Module Information

1.2.1 Block Diagram



AW-PU551 Block Diagram

1.2.2 Ordering information

Planned versions :

Model Name	Part Number of Main Chip	RAM Size	eMMC Size	Part Differentiator	Fusion
AW-PU551-6DA-0B08	MIMX8MN6DVTJZAA	512MB(4Gb)	8GB(64Gb)	Full featured, 4x A53	N/A
AW-PU551-6DA-0B16	MIMX8MN6DVTJZAA	512MB(4Gb)	16GB(128Gb)	Full featured, 4x A53	N/A
AW-PU551-6DC-0B16	MIMX8MN6DVTJZCA	512MB(4Gb)	16GB(128Gb)	No GPU, 4x A53	Immersiv3D w/ Dolby Atmos
AW-PU551-6DD-0B16	MIMX8MN6DVTJZDA	512MB(4Gb)	16GB(128Gb)	No GPU, 4x A53	Immersiv3D w/ Dolby Atmos & DTS

1.3 Specifications Table

1.3.1 General

Features	Description
Product Description	NXP i.MX 8M Nano SoM with Wi-Fi 1x1 Connectivity
Major Chipset	NXP i.MX 8M Nano, NXP 88W8987
CPU Speed (frequency)	1.5GHz
Wireless Connectivity	<ul style="list-style-type: none"> ● Use the AW-CM358 module¹. ● IEEE 802.11a/b/g/n/ac Wireless LAN 1T1R and Bluetooth 5.2. ● RF Connector: I-PEX MHF4 Connector Receptacle (20449).
USB	x1 USB 2.0 On-The-Go (OTG) interface
uSDHC	x1 Ultra Secure Digital Host Controller (uSDHC) interfaces
Ethernet	x1 Gigabit Ethernet controller with support for Energy Efficient, Ethernet (EEE), Ethernet AVB, and IEEE 1588
MIPI Interface	<ul style="list-style-type: none"> ● 4-lane MIPI CSI interface ● 4-lane MIPI DSI interface
UART	x2 Universal Asynchronous Receiver/Transmitter (UART) modules
ECSPI	x1 ECSPI modules
I²C	x3 I ² C modules
Audio Interface	<ul style="list-style-type: none"> ● x1 S/PDIF input and output, including a new Raw Capture input mode ● x5 synchronous audio interface (SAI) modules supporting I2S, AC97, TDM, codec/DSP, and DSD interfaces ● x1 SAI with 4 Tx and 4 Rx lanes ● x2 SAI with 2 Tx and 2 Rx lanes ● x2 SAI with 1 Tx and 1 Rx lanes ● x1 Pulse Density Modulation (PDM) input
Ram	512MB(4Gb) 16bit DDR3L-1600
Flash	8GB(64Gb) eMMC 5.1 / 16GB(128Gb) eMMC 5.1 (Option)
Dimension	46 X 39 X 2.95mm (typ)
Package	Stamp LGA
Weight	8g

¹ For the detail, please refer to the datasheet of AW-CM358.

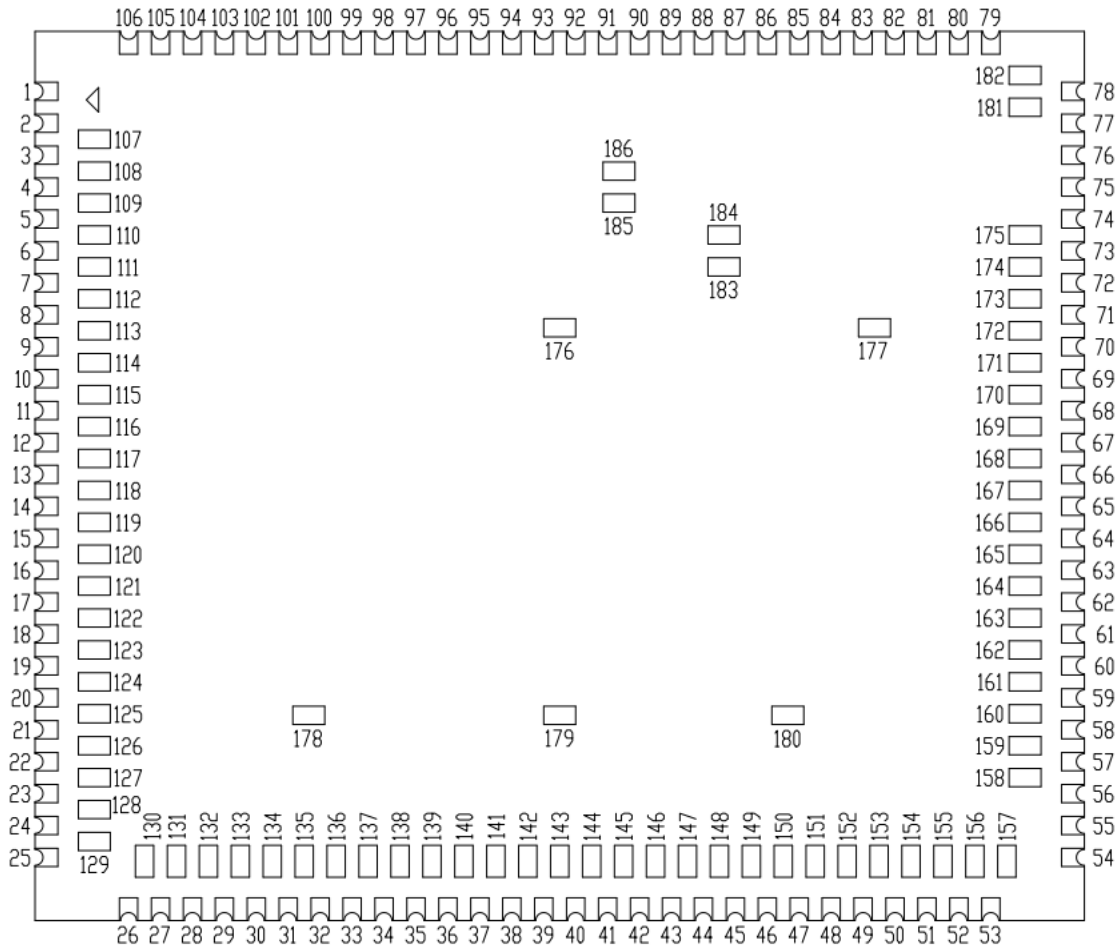
1.3.2 Operating Conditions

Features	Description
Operating Conditions	
Voltage	VBAT: 5V +/-10%
Operating Temperature	0°C to +70°C ²
Operating Humidity	less than 85%R.H.
Storage Temperature	-25°C to +85°C
Storage Humidity	less than 60%R.H.
ESD Protection	
Human Body Model	1KV per JS-001-2017
Changed Device Model	250V per JS-002-2018

² Based on temperature Tj of i.MX 8M Nano is 0 ~ +95°C. If you have questions, please contact your AzureWave FAE.

2. Pin Definition

2.1 Pin Map



PIN DEFINED (TOP VIEW)

2.2 Pin Table

Pin No	Definition	Basic Description	Voltage	Type
1	GND	Connect to GND		
2	ECSPI2_MISO	Master In Slave Out; Also Refer to Table10 for functional multiplex information.	3.3V	I
3	GND	Connect to GND		
4	ECSPI2_MOSI	Master Out Slave In; Also Refer to Table10 for functional multiplex information.	3.3V	O
5	GND	Connect to GND		
6	GND	Connect to GND		
7	SAI3_MCLK	GPIO; Refer to Table6 for functional multiplex information.	3.3V	I/O
8	SAI3_TXFS	GPIO; Refer to Table6 for functional multiplex information.	3.3V	I/O
9	SAI3_TXD	GPIO; Refer to Table6 for functional multiplex information.	3.3V	I/O
10	SAI3_TXC	GPIO; Refer to Table6 for functional multiplex information.	3.3V	I/O
11	SAI3_RXD	GPIO; Refer to Table6 for functional multiplex information.	3.3V	I/O
12	SAI3_RXC	GPIO; Refer to Table6 for functional multiplex information.	3.3V	I/O
13	SAI3_RXFS	GPIO; Refer to Table6 for functional multiplex information.	3.3V	I/O
14	GND	Connect to GND		
15	SPDIF_EXT_CLK	GPIO; Refer to Table6 for functional multiplex information.	3.3V	I/O
16	SPDIF_RX	GPIO; Refer to Table6 for functional multiplex information.	3.3V	I/O
17	SPDIF_TX	GPIO; Refer to Table6 for functional multiplex information.	3.3V	I/O
18	GND	Connect to GND		
19	GPIO1_IO05	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O
20	GPIO1_IO07	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O
21	GPIO1_IO09	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O
22	GPIO1_IO11	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O

23	GPIO1_IO13	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O
24	GPIO1_IO15	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O
25	GND	Connect to GND		
26	SAI5_RXD1	GPIO; Refer to Table3 for functional multiplex information.	3.3V	I/O
27	SAI5_RXD0	GPIO; Refer to Table3 for functional multiplex information.	3.3V	I/O
28	SAI5_RXFS	GPIO; Refer to Table3 for functional multiplex information.	3.3V	I/O
29	GND	Connect to GND		
30	NC	Do not connect. Leave it floating		
31	NC	Do not connect. Leave it floating		
32	NC	Do not connect. Leave it floating		
33	NC	Do not connect. Leave it floating		
34	NC	Do not connect. Leave it floating		
35	NC	Do not connect. Leave it floating		
36	GND	Connect to GND		
37	SYS_nRST	System Reset; Active low		I
38	GND	Connect to GND		
39	NC	Do not connect. Leave it floating		
40	NC	Do not connect. Leave it floating		
41	NC	Do not connect. Leave it floating		
42	NC	Do not connect. Leave it floating		
43	NC	Do not connect. Leave it floating		
44	GND	Connect to GND		
45	NC	Do not connect. Leave it floating		
46	SAI2_RXFS	GPIO; Refer to Table5 for functional multiplex information.	1.8V	I/O
47	GND	Connect to GND		
48	VDD_1V8	1.8V Power supply output	1.8V	O

49	GND	Connect to GND		
50	VSYS_5V	5V Power supply input	5V	I
51	VSYS_5V	5V Power supply input	5V	I
52	GND	Connect to GND		
53	VDD_3V3	3.3V Power supply output	3.3V	O
54	SD2_nRST*1	GPIO; Refer to Table1 for functional multiplex information.	1.8V/3.3V	I/O
55	SD2_DATA0*1	GPIO; Refer to Table1 for functional multiplex information.	1.8V/3.3V	I/O
56	SD2_DATA1*1	GPIO; Refer to Table1 for functional multiplex information.	1.8V/3.3V	I/O
57	SD2_CMD*1	GPIO; Refer to Table1 for functional multiplex information.	1.8V/3.3V	I/O
58	SD2_CLK*1	GPIO; Refer to Table1 for functional multiplex information.	1.8V/3.3V	I/O
59	SD2_DATA2*1	GPIO; Refer to Table1 for functional multiplex information.	1.8V/3.3V	I/O
60	SD1_STROBE	GPIO; Refer to Table1 for functional multiplex information.	1.8V	I/O
61	GND	Connect to GND		
62	ENET_TXC	Transmit Clock; Also Refer to Table9	NVCC_ENET	I/O
63	ENET_TD2	Transmit data 2; Also Refer to Table9	NVCC_ENET	O
64	ENET_TD0	Transmit data 0; Also Refer to Table9	NVCC_ENET	O
65	ENET_RX_CTL	Receive Control; Also Refer to Table9	NVCC_ENET	I
66	ENET_RD0	Receive data 0; Also Refer to Table9	NVCC_ENET	I
67	ENET_RD1	Receive data 1; Also Refer to Table9	NVCC_ENET	I
68	ENET_MDC	Management data clock reference; Also Refer to Table9	NVCC_ENET	I/O
69	NVCC_ENET	ENET vio supply	NVCC_ENET	I
70	UART2_TXD	GPIO; Refer to Table8 for functional multiplex information.	1.8V	O
71	GND	Connect to GND		
72	ONOFF	CPU ONOFF		I
73	GND	Connect to GND		
74	USB1_DP	USB data plus		I/O

75	USB1_DN	USB data minus		I/O
76	GND	Connect to GND		
77	USB1_VBUS	UDB OTG bus power		I
78	GND	Connect to GND		
79	CSI_DN3	MIPI-CSI Data Lane 3.		
80	CSI_DP3	MIPI-CSI Data Lane 3.		
81	CSI_DN2	MIPI-CSI Data Lane 2.		
82	CSI_DP2	MIPI-CSI Data Lane 2.		
83	CSI_CKP	MIPI-CSI Clock Lane.		
84	CSI_CKN	MIPI-CSI Clock Lane.		
85	CSI_DP1	MIPI-CSI Data Lane 1.		
86	CSI_DN1	MIPI-CSI Data Lane 1.		
87	CSI_DN0	MIPI-CSI Data Lane 0.		
88	CSI_DP0	MIPI-CSI Data Lane 0.		
89	GND	Connect to GND		
90	DSI_DN3	MIPI-DSI Data Lane 3.		
91	DSI_DP3	MIPI-DSI Data Lane 3.		
92	DSI_DN2	MIPI-DSI Data Lane 2.		
93	DSI_DP2	MIPI-DSI Data Lane 2.		
94	DSI_CKN	MIPI-DSI Clock Lane.		
95	DSI_CKP	MIPI-DSI Clock Lane.		
96	DSI_DN1	MIPI-DSI Data Lane 1.		
97	DSI_DP1	MIPI-DSI Data Lane 1.		
98	DSI_DN0	MIPI-DSI Data Lane 0.		
99	DSI_DP0	MIPI-DSI Data Lane 0.		
100	GND	Connect to GND		

101	I2C4_SCL	GPIO; Refer to Table7 for functional multiplex information.	1.8V	I/O
102	I2C4_SDA	GPIO; Refer to Table7 for functional multiplex information.	1.8V	I/O
103	I2C2_SCL	GPIO; Refer to Table7 for functional multiplex information.	1.8V	I/O
104	I2C3_SCL	GPIO; Refer to Table7 for functional multiplex information.	1.8V	I/O
105	I2C3_SDA	GPIO; Refer to Table7 for functional multiplex information.	1.8V	I/O
106	I2C2_SDA	GPIO; Refer to Table7 for functional multiplex information.	1.8V	I/O
107	ECSPI2_SS0	Standard Serial Clock; Also Refer to Table10 for functional multiplex information.	3.3V	I/O
108	GND	Connect to GND		
109	ECSPI2_SCLK	Slave Select; Also Refer to Table10 for functional multiplex information.	3.3V	O
110	GND	Connect to GND		
111	GND	Connect to GND		
112	GND	Connect to GND		
113	GND	Connect to GND		
114	GND	Connect to GND		
115	GND	Connect to GND		
116	GND	Connect to GND		
117	GND	Connect to GND		
118	GND	Connect to GND		
119	GND	Connect to GND		
120	GND	Connect to GND		
121	GND	Connect to GND		
122	GND	Connect to GND		
123	GPIO1_IO01	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O
124	GPIO1_IO06	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O
125	GPIO1_IO08	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O
126	GPIO1_IO10	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O

127	GPIO1_IO12	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O
128	GPIO1_IO14	GPIO; Refer to Table2 for functional multiplex information.	1.8V	I/O
129	SAI5_RXD2	GPIO; Refer to Table3 for functional multiplex information.	3.3V	I/O
130	SAI5_RXD3	GPIO; Refer to Table3 for functional multiplex information.	3.3V	I/O
131	SAI5_RXC	GPIO; Refer to Table3 for functional multiplex information.	3.3V	I/O
132	GND	Connect to GND		
133	SAI5_MCLK	GPIO; Refer to Table3 for functional multiplex information.	3.3V	I/O
134	GND	Connect to GND		
135	NC	Do not connect. Leave it floating		
136	NC	Do not connect. Leave it floating		
137	NC	Do not connect. Leave it floating		
138	NC	Do not connect. Leave it floating		
139	GND	Connect to GND		
140	GND	Connect to GND		
141	GND	Connect to GND		
142	GND	Connect to GND		
143	NC	Do not connect. Leave it floating		
144	NC	Do not connect. Leave it floating		
145	NC	Do not connect. Leave it floating		
146	NC	Do not connect. Leave it floating		
147	NC	Do not connect. Leave it floating		
148	NC	Do not connect. Leave it floating		
149	SAI2_MCLK	GPIO; Refer to Table5 for functional multiplex information.	1.8V	I/O
150	SAI2_RXC	GPIO; Refer to Table5 for functional multiplex information.	1.8V	I/O
151	GND	Connect to GND		
152	VDD_1V8	1.8V Power supply output	1.8V	O

153	GND	Connect to GND		
154	VSYS_5V	5V Power supply input	5V	I
155	VSYS_5V	5V Power supply input	5V	I
156	GND	Connect to GND		
157	VDD_3V3	3.3V Power supply output	3.3V	O
158	SD2_NCD*1	GPIO; Refer to Table1 for functional multiplex information.	1.8V/3.3V	I/O
159	SD2_WP*1	GPIO; Refer to Table1 for functional multiplex information.	1.8V/3.3V	I/O
160	SD2_DATA3*1	GPIO; Refer to Table1 for functional multiplex information.	1.8V/3.3V	I/O
161	GND	Connect to GND		
162	NC	Do not connect. Leave it floating		
163	GND	Connect to GND		
164	ENET_TX_CTL	Transmit Control; Also Refer to Table9 for functional multiplex information.	NVCC_ENET	O
165	ENET_TD3	Transmit data 3; Also Refer to Table9 for functional multiplex information.	NVCC_ENET	O
166	ENET_TD1	Transmit data 1; Also Refer to Table9 for functional multiplex information.	NVCC_ENET	O
167	ENET_RXC	Receive Clock; Also Refer to Table9 for functional multiplex information.	NVCC_ENET	I/O
168	ENET_RD2	Receive data 2; Also Refer to Table9 for functional multiplex information.	NVCC_ENET	I
169	ENET_RD3	Receive data 3; Also Refer to Table9 for functional multiplex information.	NVCC_ENET	I
170	ENET_MDIO	Management data; Also Refer to Table9 for functional multiplex information.	NVCC_ENET	I/O
171	GND	Connect to GND		
172	UART2_RXD	GPIO; Refer to Table8 for functional multiplex information.	1.8V	I
173	USB1_ID	USB OTG ID signal		I
174	BOOT_MODE0	Boot mode configuration pins	1.8V	I
175	BOOT_MODE1	Boot mode configuration pins	1.8V	I
176	GND	Connect to GND		
177	GND	Connect to GND		
178	GND	Connect to GND		

179	GND	Connect to GND		
180	GND	Connect to GND		
181	UART4_RXD	GPIO; Refer to Table8 for functional multiplex information.	1.8V	I
182	UART4_TXD	GPIO; Refer to Table8 for functional multiplex information.	1.8V	I
183	NC	Do not connect. Leave it floating		
184	NC	Do not connect. Leave it floating		
185	NC	Do not connect. Leave it floating		
186	NC	Do not connect. Leave it floating		

*1 SD2 can be set as 1.8V or 3.3V by software.

2.3 Pin Multiplexing Tables³

Multiple usage pins are used to conserve pin consumption for different features. The AW-PU551 devices can be used in many different applications but each application will not utilize all the on chip features. As a result, some of the features share the same pin. Most of the multiple usage pins can be used as a GPIO pin as well.

Table 1 (SD)

Pin Name	Default	FUNC0	FUNC1	FUNC2
SD1_STROBE	gpio2.IO[11]	usdhc1.STROBE		UART3_CTS_B
SD2_CD_B	gpio2.IO[12]	usdhc2.CD_B		
SD2_CLK	gpio2.IO[13]	usdhc2.CLK	SAI5_RX_SYNC	SAI5_MCLK
SD2_CMD	gpio2.IO[14]	usdhc2.CMD	SAI5_RX_BCLK	PDM_CLK
SD2_DATA0	gpio2.IO[15]	usdhc2.DATA0	SAI5_RX_DATA[0]	PDM_BIT[0]
SD2_DATA1	gpio2.IO[16]	usdhc2.DATA1	SAI5_TX_SYNC	PDM_BIT[1]
SD2_DATA2	gpio2.IO[17]	usdhc2.DATA2	SAI5_TX_BCLK	PDM_BIT[2]
SD2_DATA3	gpio2.IO[18]	usdhc2.DATA3	SAI5_TX_DATA[0]	PDM_BIT[3]
SD2_RESET_B	gpio2.IO[19]	usdhc2.RESET_B		
SD2_WP	gpio2.IO[20]	usdhc2.WP		

³ For program GPIOs, please confirm with AZW software team.

Table 1 (SD) continued

Pin Name	FUNC3	FUNC4	FUNC5	FUNC6	FUNC7
SD1_STROBE	I2C3_SDA	UART3_CTS_B	gpio2.IO[11]		
SD2_CD_B			gpio2.IO[12]		
SD2_CLK	UART4_RX	SAI5_MCLK	gpio2.IO[13]	reserved	reserved
SD2_CMD	UART4_TX	PDM_CLK	gpio2.IO[14]	reserved	reserved
SD2_DATA0	UART2_RX	PDM_BIT[0]	gpio2.IO[15]	reserved	reserved
SD2_DATA1	UART2_TX	PDM_BIT[1]	gpio2.IO[16]	reserved	reserved
SD2_DATA2	SPDIF_OUT	PDM_BIT[2]	gpio2.IO[17]	reserved	reserved
SD2_DATA3	SPDIF_IN	PDM_BIT[3]	gpio2.IO[18]	reserved	
SD2_RESET_B			gpio2.IO[19]	reserved	
SD2_WP			gpio2.IO[20]	CORESIGHT_EVENT1	reserved

Table 2 (GPIOs)

Pin Name	Default	FUNC0	FUNC1	FUNC2
GPIO1_IO01	gpio1.IO[1]	gpio1.IO[1]	pwm1.OUT	
GPIO1_IO05	gpio1.IO[5]	gpio1.IO[5]	m4.NMI	
GPIO1_IO06	gpio1.IO[6]	gpio1.IO[6]	enet1.MDC	
GPIO1_IO07	gpio1.IO[7]	gpio1.IO[7]	enet1.MDIO	
GPIO1_IO08	gpio1.IO[8]	gpio1.IO[8]		PWM1_OUT
GPIO1_IO09	gpio1.IO[9]	gpio1.IO[9]		PWM2_OUT
GPIO1_IO10	gpio1.IO[10]	gpio1.IO[10]		PWM3_OUT
GPIO1_IO11	gpio1.IO[11]	gpio1.IO[11]	PWM2_OUT	
GPIO1_IO12	gpio1.IO[12]	gpio1.IO[12]	usb1.OTG_PWR	
GPIO1_IO13	gpio1.IO[13]	gpio1.IO[13]	usb1.OTG_OC	
GPIO1_IO14	gpio1.IO[14]	gpio1.IO[14]		
GPIO1_IO15	gpio1.IO[15]	gpio1.IO[15]		

Table 2 (GPIOs) continued

Pin Name	FUNC4	FUNC5	FUNC6	FUNC7
GPIO1_IO01		anamix.REF_CLK_24M	reserved	reserved
GPIO1_IO05		ccmsrcgpcmix.PMIC_READY	reserved	reserved
GPIO1_IO06		usdhc1.CD_B	reserved	reserved
GPIO1_IO07		usdhc1.WP	reserved	reserved
GPIO1_IO08		usdhc2.RESET_B	reserved	reserved
GPIO1_IO09	usdhc3.RESET_B	sdma2.XT_EVENT[0]	reserved	reserved
GPIO1_IO10				reserved
GPIO1_IO11	usdhc3.VSELECT	ccmsrcgpcmix.PMIC_READY	reserved	reserved
GPIO1_IO12		sdma2.EXT_EVENT[1]	reserved	reserved
GPIO1_IO13		pwm2.OUT	reserved	reserved
GPIO1_IO14	usdhc3.CD_B	pwm3.OUT	reserved	reserved
GPIO1_IO15	usdhc3.WP	pwm4.OUT	reserved	reserved

Table 3 (SAI5)

Pin Name	Default	FUNC0	FUNC3
SAI5_RXFS	gpio3.IO[19]	sai5.RX_SYNC	
SAI5_RXC	gpio3.IO[20]	sai5.RX_BCLK	
SAI5_RXD0	gpio3.IO[21]	sai5.RX_DATA[0]	
SAI5_RXD1	gpio3.IO[22]	sai5.RX_DATA[1]	sai5.TX_SYNC
SAI5_RXD2	gpio3.IO[23]	sai5.RX_DATA[2]	sai5.TX_BCLK
SAI5_RXD3	gpio3.IO[24]	sai5.RX_DATA[3]	sai5.TX_DATA[0]
SAI5_MCLK	gpio3.IO[25]	sai5.MCLK	

Table 3 (SAI5) continued

Pin Name	FUNC4	FUNC5	FUNC6	FUNC7
SAI5_RXFS		gpio3.IO[19]		reserved
SAI5_RXC	pdm.CLK	gpio3.IO[20]		reserved
SAI5_RXD0	pdm.BIT_STREAM[0]	gpio3.IO[21]		
SAI5_RXD1	pdm.BIT_STREAM[1]	gpio3.IO[22]		
SAI5_RXD2	pdm.BIT_STREAM[2]	gpio3.IO[23]		
SAI5_RXD3	pdm.BIT_STREAM[3]	gpio3.IO[24]		
SAI5_MCLK		gpio3.IO[25]	reserved	

Table 5 (SAI2)

Pin Name	Default	FUNC0	FUNC1	FUNC2
SAI2_RXFS	gpio4.IO[21]	sai2.RX_SYNC	sai5.TX_SYNC	sai5.TX_DATA[1]
SAI2_RXC	gpio4.IO[22]	sai2.RX_BCLK	sai5.TX_BCLK	
SAI2_RXD0	gpio4.IO[23]	sai2.RX_DATA[0]	sai5.TX_DATA[0]	
SAI2_TXFS	gpio4.IO[24]	sai2.TX_SYNC	sai5.TX_DATA[1]	
SAI2_TXC	gpio4.IO[25]	sai2.TX_BCLK	sai5.TX_DATA[2]	
SAI2_TXD0	gpio4.IO[26]	sai2.TX_DATA[0]	sai5.TX_DATA[3]	
SAI2_MCLK	gpio4.IO[27]	sai2.MCLK	sai5.MCLK	

Table 5 (SAI2) continued

Pin Name	FUNC3	FUNC4	FUNC5	FUNC6	FUNC7
SAI2_RXFS	sai2.RX_DATA[1]	uart1.TX	gpio4.IO[21]	PDM_BIT [2]	reserved
SAI2_RXC		uart1.RX	gpio4.IO[22]	PDM_BIT [1]	reserved
SAI2_RXD0	sai2.TX_DATA[1]	uart1.RTS_B	gpio4.IO[23]	PDM_BIT [3]	reserved
SAI2_TXFS	sai2.TX_DATA[1]	uart1.CTS_B	gpio4.IO[24]	PDM_BIT [2]	reserved
SAI2_TXC			gpio4.IO[25]	PDM_BIT [1]	reserved
SAI2_TXD0			gpio4.IO[26]		reserved
SAI2_MCLK			gpio4.IO[27]	SAI3_MCLK	reserved

Table 6 (SAI3, SPDIF)

Pin Name	Default	FUNC0	FUNC1	FUNC2
SAI3_RXFS	gpio4.IO[28]	sai3.RX_SYNC	gpt1.CAPTURE1	sai5.RX_SYNC
SAI3_RXC	gpio4.IO[29]	sai3.RX_BCLK	gpt1.CLK	sai5.RX_BCLK
SAI3_RXD	gpio4.IO[30]	sai3.RX_DATA[0]	gpt1.COMPARE1	sai5.RX_DATA[0]
SAI3_TXFS	gpio4.IO[31]	sai3.TX_SYNC	gpt1.CAPTURE2	sai5.RX_DATA[1]
SAI3_TXC	gpio5.IO[0]	sai3.TX_BCLK	gpt1.COMPARE2	sai5.RX_DATA[2]
SAI3_TXD	gpio5.IO[1]	sai3.TX_DATA[0]	gpt1.COMPARE3	sai5.RX_DATA[3]
SAI3_MCLK	gpio5.IO[2]	sai3.MCLK	pwm4.OUT	sai5.MCLK
SPDIF_TX	gpio5.IO[3]	spdif1.OUT	pwm3.OUT	
SPDIF_RX	gpio5.IO[4]	spdif1.IN	pwm2.OUT	
SPDIF_EXT_CLK	gpio5.IO[5]	spdif1.EXT_CLK	pwm1.OUT	

Table 6 (SAI3, SPDIF) continued

Pin Name	FUNC3	FUNC4	FUNC5	FUNC6	FUNC7
SAI3_RXFS	sai3.RX_DATA[1]	SPDIF_IN	gpio4.IO[28]	PDM_BIT [0]	reserved
SAI3_RXC	sai3.RX_DATA[1]	uart2.CTS_B	gpio4.IO[29]	PDM_CLK	reserved
SAI3_RXD	sai3.TX_DATA[1]	uart2.RTS_B	gpio4.IO[30]	PDM_BIT [1]	reserved
SAI3_TXFS	sai3.TX_DATA[1]	uart2.RX	gpio4.IO[31]	PDM_BIT [3]	reserved
SAI3_TXC		uart2.TX	gpio5.IO[0]	PDM_BIT [2]	reserved
SAI3_TXD		SPDIF_EXT_CLK	gpio5.IO[1]		reserved
SAI3_MCLK		SPDIF_OUT	gpio5.IO[2]	SPDIF_IN	reserved
SPDIF_TX			gpio5.IO[3]		reserved
SPDIF_RX			gpio5.IO[4]		reserved
SPDIF_EXT_CLK			gpio5.IO[5]		reserved

Table 7 (I2C)

Pin Name	Default	FUNC0	FUNC1	FUNC2	FUNC3	FUNC5	FUNC7
I2C2_SCL	gpio5.IO[16]	i2c2.SCL	enet1.1588_EVENT1_IN	usdhc3.CD_B	ECSPI1_MISO	gpio5.IO[16]	reserved
I2C2_SDA	gpio5.IO[17]	i2c2.SDA	enet1.1588_EVENT1_OUT	usdhc3.WP	ECSPI1_SS0	gpio5.IO[17]	reserved
I2C3_SCL	gpio5.IO[18]	i2c3.SCL	pwm4.OUT	gpt2.CLK	ECSPI2_SCLK	gpio5.IO[18]	reserved
I2C3_SDA	gpio5.IO[19]	i2c3.SDA	pwm3.OUT	gpt3.CLK	ECSPI2_MOSI	gpio5.IO[19]	reserved
I2C4_SCL	gpio5.IO[20]	i2c4.SCL	pwm2.OUT		ECSPI2_MISO	gpio5.IO[20]	reserved
I2C4_SDA	gpio5.IO[21]	i2c4.SDA	pwm1.OUT		ECSPI2_SS0	gpio5.IO[21]	reserved

Table 8 (UART)

Pin Name	Default	FUNC0	FUNC1	FUNC3	FUNC5	FUNC7
UART2_RXD	gpio5.IO[24]	uart2.RX	ecspi3.MISO	GPT1_COMPARE3	gpio5.IO[24]	reserved
UART2_TXD	gpio5.IO[25]	uart2.TX	ecspi3.SS0	GPT1_COMPARE2	gpio5.IO[25]	reserved
UART4_RXD	gpio5.IO[28]	uart4.RX	uart2.CTS_B	GPT1_COMPARE1	gpio5.IO[28]	reserved
UART4_TXD	gpio5.IO[29]	uart4.TX	uart2.RTS_B	GPT1_CAPTURE1	gpio5.IO[29]	reserved

Table 9 (Ethernet)

Pin Name	Default	FUNC0	FUNC1	FUNC2
ENET_MDC	gpio1.IO[16]	enet1.MDC		SAI6_TX_DATA[0]
ENET_MDIO	gpio1.IO[17]	enet1.MDIO		SAI6_TX_SYNC
ENET_TD3	gpio1.IO[18]	enet1.RGMII_TD3		SAI6_TX_BCLK
ENET_TD2	gpio1.IO[19]	enet1.RGMII_TD2	INPUT=enet1.TX_CLK OUTPUT=ccmsrcgpcmix. ENET_REF_CLK_ROOT	SAI6_RX_DATA[0]
ENET_TD1	gpio1.IO[20]	enet1.RGMII_TD1		SAI6_RX_SYNC
ENET_TD0	gpio1.IO[21]	enet1.RGMII_TD0		SAI6_RX_BCLK
ENET_TX_CTL	gpio1.IO[22]	enet1.RGMII_TX_CTL		SAI6_MCLK
ENET_TXC	gpio1.IO[23]	enet1.RGMII_TXC	enet1.TX_ER	SAI7_TX_DATA[0]
ENET_RX_CTL	gpio1.IO[24]	enet1.RGMII_RX_CTL		SAI7_TX_SYNC
ENET_RXC	gpio1.IO[25]	enet1.RGMII_RXC	enet1.RX_ER	SAI7_TX_BCLK
ENET_RD0	gpio1.IO[26]	enet1.RGMII_RD0		SAI7_RX_DATA[0]
ENET_RD1	gpio1.IO[27]	enet1.RGMII_RD1		SAI7_RX_SYNC
ENET_RD2	gpio1.IO[28]	enet1.RGMII_RD2		SAI7_RX_BCLK
ENET_RD3	gpio1.IO[29]	enet1.RGMII_RD3		SAI7_MCLK

Table 9 (Ethernet) continued

Pin Name	FUNC3	FUNC4	FUNC5	FUNC6
ENET_MDC	PDM_BIT[3]	SPDIF_OUT	gpio1.IO[16]	USDHC3_STROBE
ENET_MDIO	PDM_BIT[2]	SPDIF_IN	gpio1.IO[17]	USDHC3_DATA5
ENET_TD3	PDM_BIT[1]	SPDIF_EXT_CLK	gpio1.IO[18]	USDHC3_DATA6
ENET_TD2	PDM_BIT[3]		gpio1.IO[19]	USDHC3_DATA7
ENET_TD1	PDM_BIT[2]		gpio1.IO[20]	USDHC3_CD_B
ENET_TD0	PDM_BIT[1]		gpio1.IO[21]	USDHC3_WP
ENET_TX_CTL			gpio1.IO[22]	USDHC3_DATA0
ENET_TXC			gpio1.IO[23]	USDHC3_DATA1
ENET_RX_CTL	PDM_BIT[3]		gpio1.IO[24]	USDHC3_DATA2
ENET_RXC	PDM_BIT[2]		gpio1.IO[25]	USDHC3_DATA3
ENET_RD0	PDM_BIT[1]		gpio1.IO[26]	USDHC3_DATA4
ENET_RD1	PDM_BIT[0]		gpio1.IO[27]	USDHC3_RESET_B
ENET_RD2	PDM_CLK		gpio1.IO[28]	USDHC3_CLK
ENET_RD3	SPDIF_IN		gpio1.IO[29]	USDHC3_CMD

Table 10 (ECSPI)

Pin Name	Default	FUNC0	FUNC1	FUNC2	FUNC3
ECSPI2_SCLK	gpio5.IO[10]	ecspi2.SCLK	uart4.RX	I2C3_SCL	SAI5_RX_DATA[2]
ECSPI2_MOSI	gpio5.IO[11]	ecspi2.MOSI	uart4.TX	I2C3_SDA	SAI5_RX_DATA[3]
ECSPI2_MISO	gpio5.IO[12]	ecspi2.MISO	uart4.CTS_B	I2C4_SCL	SAI5_MCLK
ECSPI2_SS0	gpio5.IO[13]	ecspi2.SS0	uart4.RTS_B	I2C4_SDA	

Table 10 (ECSPI) continued

Pin Name	FUNC4	FUNC5	FUNC7
ECSPI2_SCLK	SAI5_TX_BCLK	gpio5.IO[10]	reserved
ECSPI2_MOSI	SAI5_TX_DATA[0]	gpio5.IO[11]	reserved
ECSPI2_MISO		gpio5.IO[12]	reserved
ECSPI2_SS0		gpio5.IO[13]	reserved

3. Electrical Characteristics

3.1 Absolute Maximum Ratings

Symbol	Parameter	Minimum	Typical	Maximum	Unit
VSYS_5V	DC supply input	-0.3	--	+6	V

3.2 Recommended Operating Conditions

Symbol	Parameter	Minimum	Typical	Maximum	Unit
VSYS_5V	DC supply input	4.5	5	5.5	V
NVCC_ENET	Power supply for Ethernet	1.65	1.8	1.95	V
		2.25	2.5	2.75	V
		3	3.3	3.6	V

3.3 Digital IO Pin DC Characteristics

For VDD = 1.8V

Symbol	Parameter	Minimum	Typical	Maximum	Unit
VOH	Output High Voltage	0.8 x VDD	-	VDD	V
VOL	Output low level	0	-	0.2 x VDD	V
VIH	Input High level	0.7 x VDD	-	VDD + 0.3	V
VIL	Input low level	-0.3	-	0.3 x VDD	V

For VDD = 3.3V

Symbol	Parameter	Minimum	Typical	Maximum	Unit
VOH	Output High Voltage	0.8 x VDD	-	VDD	V
VOL	Output low level	0	-	0.2 x VDD	V
VIH	Input High level	0.7 x VDD	-	VDD + 0.3	V
VIL	Input low level	-0.3	-	0.3 x VDD	V

3.4 Interface

3.4.1 ECSPI timing parameters

This section describes the timing parameters of the ECSPI blocks. The ECSPI have separate timing parameters for master and slave modes.

3.4.1.1 ECSPI Master mode timing

Figure 1 depicts the timing of ECSPI in master mode. Table 11 lists the ECSPI master mode timing characteristics.

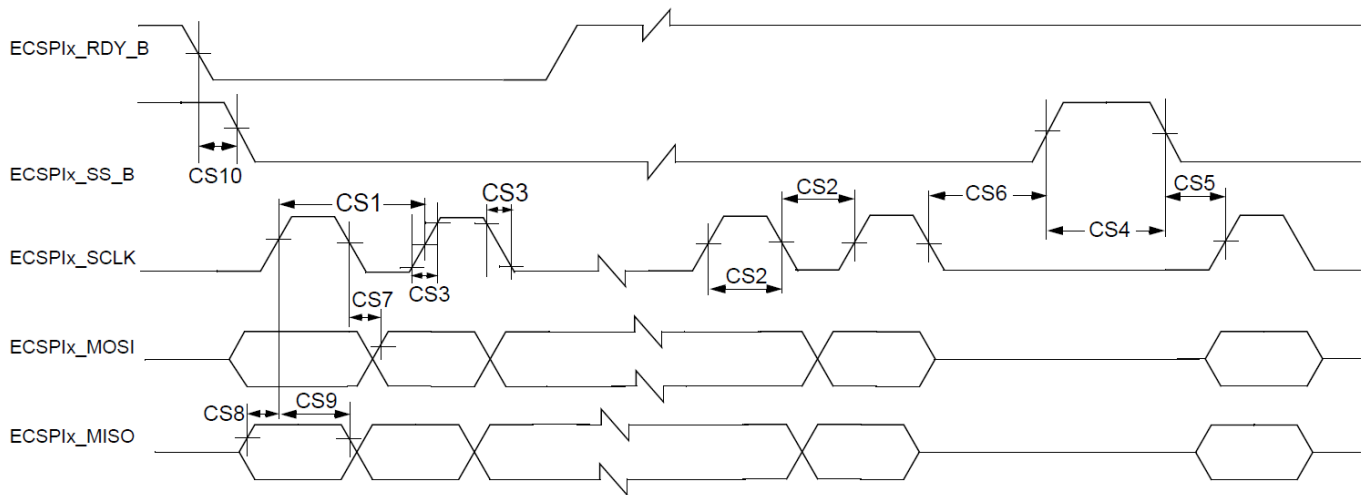


Figure 1 ECSPI Master mode timing diagram

Table 11 ECSPI Master mode timing diagram

ID	Parameter	Symbol	Min	Max	Unit
CS1	ECSPiX_SCLK Cycle Time–Read ECSPiX_SCLK Cycle Time–Write	t_{clk}	43 15	—	ns
CS2	ECSPiX_SCLK High or Low Time–Read ECSPiX_SCLK High or Low Time–Write	t_{SW}	21.5 7	—	ns
CS3	ECSPiX_SCLK Rise or Fall ¹	$t_{RISE/FALL}$	—	—	ns
CS4	ECSPiX_SS_B pulse width	t_{CSLH}	Half ECSPiX_SCLK period	—	ns
CS5	ECSPiX_SS_B Lead Time (CS setup time)	t_{SCS}	Half ECSPiX_SCLK period - 4	—	ns
CS6	ECSPiX_SS_B Lag Time (CS hold time)	t_{HCS}	Half ECSPiX_SCLK period - 2	—	ns
CS7	ECSPiX_MOSI Propagation Delay ($C_{LOAD} = 20$ pF)	t_{PDmosi}	-1	1	ns
CS8	ECSPiX_MISO Setup Time	t_{Smiso}	18	—	ns
CS9	ECSPiX_MISO Hold Time	t_{Hmiso}	0	—	ns
CS10	RDY to ECSPiX_SS_B Time ²	t_{SDRY}	5	—	ns

3.4.1.2 ECSPi Slave mode timing

Figure 2 depicts the timing of ECSPi in Slave mode. Table 12 lists the ECSPi Slave mode timing characteristics.

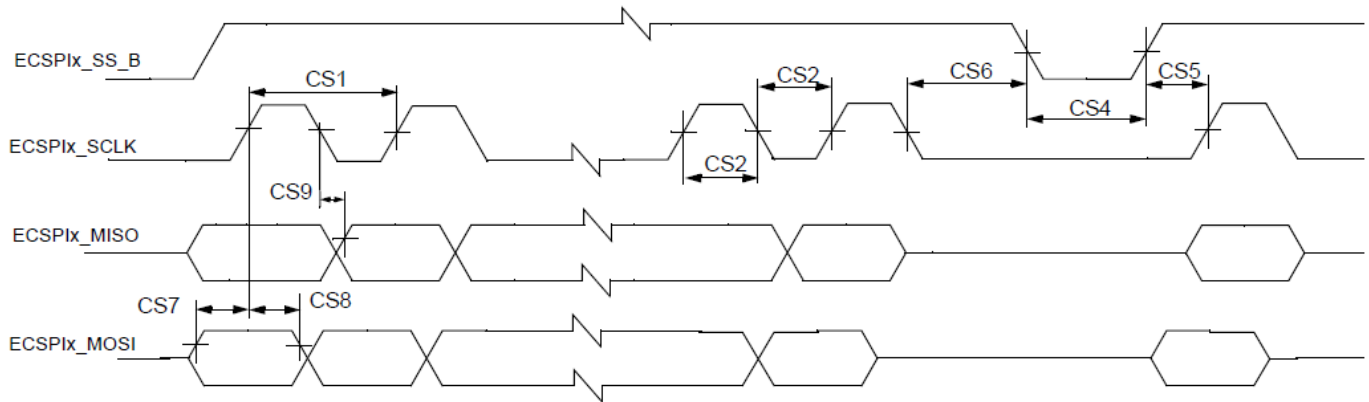


Figure 2 ECSPi Slave mode timing diagram

Table 12 ECSPi Slave mode timing diagram

ID	Parameter	Symbol	Min	Max	Unit
CS1	ECSPi_SCLK Cycle Time–Read ECSPi_SCLK Cycle Time–Write	t_{clk}	15 43	—	ns
CS2	ECSPi_SCLK High or Low Time–Read ECSPi_SCLK High or Low Time–Write	t_{sw}	7 21.5	—	ns
CS4	ECSPi_SS_B pulse width	t_{CSLH}	Half ECSPi_SCLK period	—	ns
CS5	ECSPi_SS_B Lead Time (CS setup time)	t_{SCS}	5	—	ns
CS6	ECSPi_SS_B Lag Time (CS hold time)	t_{HCS}	5	—	ns
CS7	ECSPi_MOSI Setup Time	t_{Smosi}	4	—	ns
CS8	ECSPi_MOSI Hold Time	t_{Hmosi}	4	—	ns
CS9	ECSPi_MISO Propagation Delay ($C_{LOAD} = 20$ pF)	t_{PDmiso}	4	19	ns

3.4.2 Ultra-high-speed SD/SDIO host interface (uSDHC) AC timing

This section describes the electrical information of the uSDHC, which includes SD(single data rate) timing, SD3.0 (dual data rate) AC timing, and SDR50/SDR104 AC timing.

3.4.2.1 SD3.0 (single data rate) AC timing

Figure 3 depicts the timing of SD3.0 (SDR), and Table 13 lists the SD3.0 (SDR) timing characteristics.

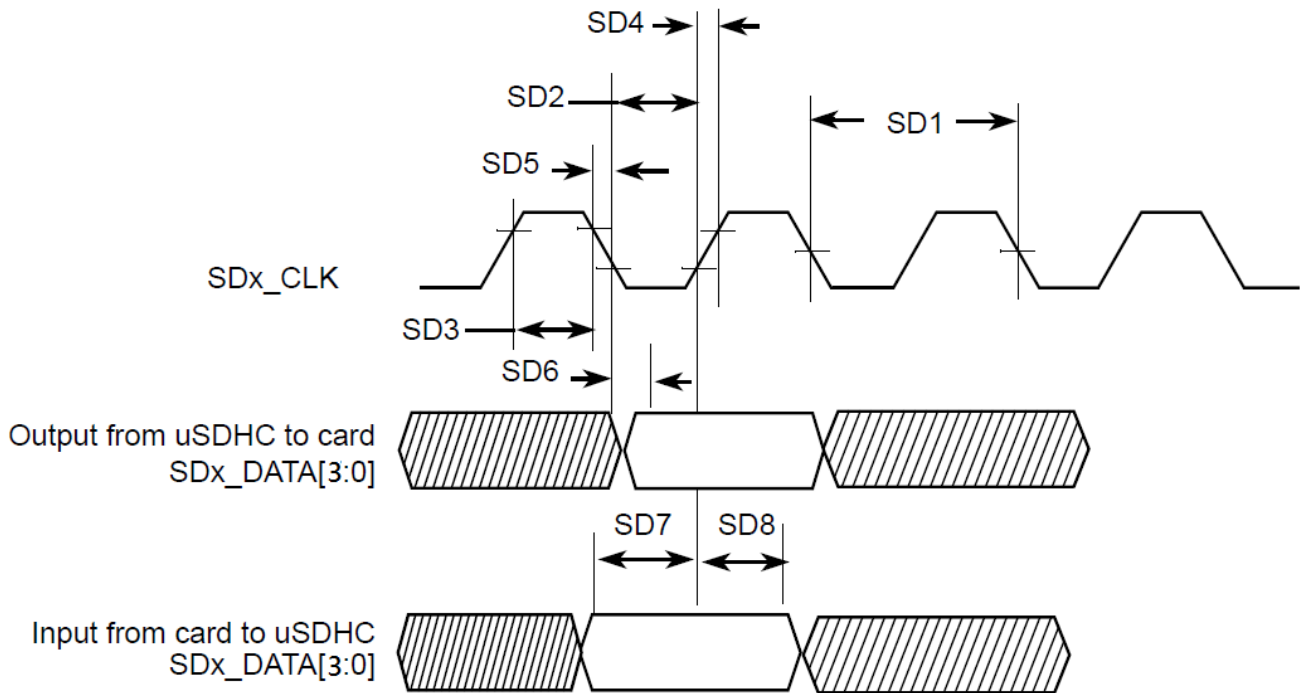


Figure 3 SD3.0 (SDR) timing

Table 13 SD3.0 (SDR) interface timing specification

ID	Parameter	Symbols	Min	Max	Unit
Card Input Clock					
SD1	Clock Frequency (Low Speed)	f_{PP}^1	0	400	kHz
	Clock Frequency (SD/SDIO Full Speed/High Speed)	f_{PP}^2	0	25/50	MHz
	Clock Frequency (MMC Full Speed/High Speed)	f_{PP}^3	0	20/52	MHz
	Clock Frequency (Identification Mode)	f_{OD}	100	400	kHz
SD2	Clock Low Time	t_{WL}	7	—	ns
SD3	Clock High Time	t_{WH}	7	—	ns
SD4	Clock Rise Time	t_{TLH}	—	3	ns
SD5	Clock Fall Time	t_{THL}	—	3	ns
uSDHC Output/Card Inputs SD_CMD, SDx_DATAx (Reference to CLK)					
SD6	uSDHC Output Delay	t_{OD}	6.6	3.6	ns
uSDHC Input/Card Outputs SD_CMD, SDx_DATAx (Reference to CLK)					
SD7	uSDHC Input Setup Time	t_{ISU}	2.5	—	ns
SD8	uSDHC Input Hold Time ⁴	t_{IH}	1.5	—	ns

¹ In Low-Speed mode, card clock must be lower than 400 kHz, voltage ranges from 2.7 to 3.6 V.

² In Normal (Full) -Speed mode for SD/SDIO card, clock frequency can be any value between 0–25 MHz. In High-speed mode, clock frequency can be any value between 0–50 MHz.

³ In Normal (Full) -Speed mode for MMC card, clock frequency can be any value between 0–20 MHz. In High-speed mode, clock frequency can be any value between 0–52 MHz.

⁴ To satisfy hold timing, the delay difference between clock input and cmd/data input must not exceed 2 ns.

3.4.2.2 SD3.0 (dual data rate) AC timing

Figure 4 depicts the timing of SD3.0 (DDR). Table 14 lists the SD3.0 (DDR) timing characteristics. Be aware that only DATA is sampled on both edges of the clock (not applicable to CMD).

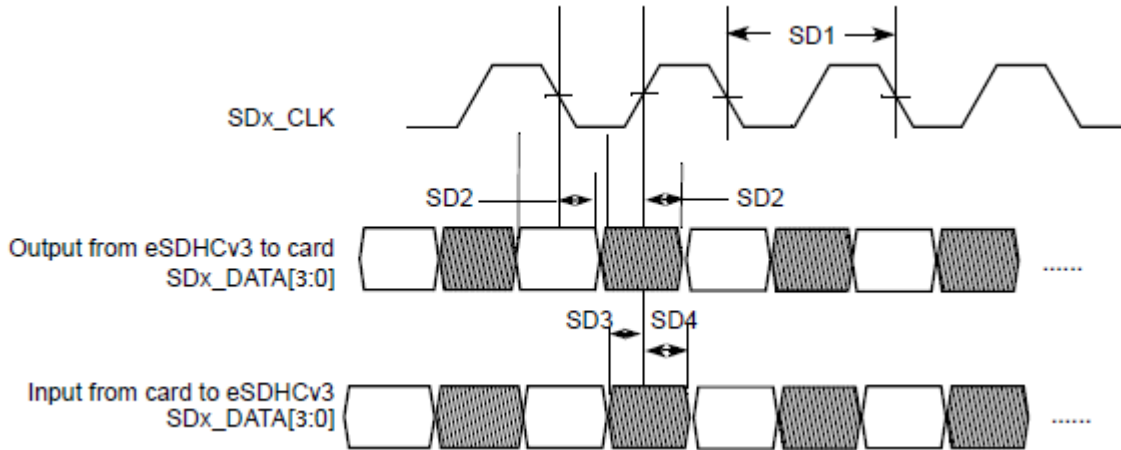


Figure 4 SD3.0 (DDR) interface timing specification

Table14 SD3.0 (DDR) interface timing specification

ID	Parameter	Symbols	Min	Max	Unit
Card Input Clock					
SD1	Clock Frequency (eMMC5.1 DDR)	f_{PP}	0	52	MHz
SD1	Clock Frequency (SD3.0 DDR)	f_{PP}	0	50	MHz
uSDHC Output / Card Inputs SD_CMD, SDx_DATAx (Reference to CLK)					
SD2	uSDHC Output Delay	t_{OD}	2.7	6.9	ns
uSDHC Input / Card Outputs SD_CMD, SDx_DATAx (Reference to CLK)					
SD3	uSDHC Input Setup Time	t_{ISU}	2.4	—	ns
SD4	uSDHC Input Hold Time	t_{IH}	1.3	—	ns

3.4.3 Ethernet controller (ENET) AC electrical specifications

The following timing specs are defined at the chip I/O pin and must be translated appropriately to arrive at timing specs/constraints for the physical interface.

3.4.3.1 RMII mode timing

Figure 5 shows RMII mode timings. Table 15 describes the timing parameters (M16–M21) shown in the figure.

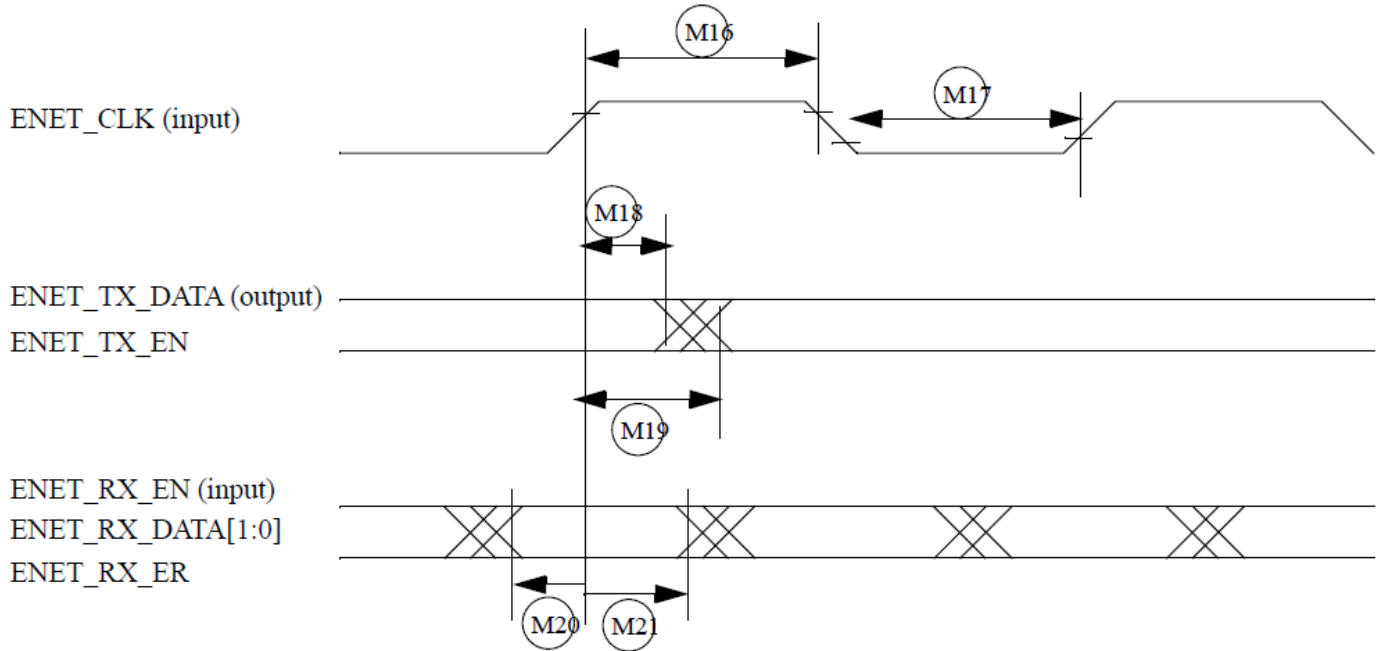


Figure 5. RMII mode signal timing diagram

Table 15. RMII signal timing

ID	Characteristic	Min.	Max.	Unit
M16	ENET_CLK pulse width high	35%	65%	ENET_CLK period
M17	ENET_CLK pulse width low	35%	65%	ENET_CLK period
M18	ENET_CLK to ENET0_TXD[1:0], ENET_TX_DATA invalid	4	—	ns
M19	ENET_CLK to ENET0_TXD[1:0], ENET_TX_DATA valid	—	15	ns
M20	ENET_RX_DATAD[1:0], ENET_RX_EN(ENET_RX_EN), ENET_RX_ER to ENET_CLK setup	4	—	ns
M21	ENET_CLK to ENET_RX_DATAD[1:0], ENET_RX_EN, ENET_RX_ER hold	2	—	ns

3.4.3.2 RGMII signal switching specifications

The following timing specifications meet the requirements for RGMII interfaces for a range of transceiver devices.

Table16. RGMII signal switching specifications¹

Symbol	Description	Min.	Max.	Unit
T_{cyc}^2	Clock cycle duration	7.2	8.8	ns
T_{skewT}^3	Data to clock output skew at transmitter	-500	500	ps
T_{skewR}^3	Data to clock input skew at receiver	1	2.6	ns
Duty_G ⁴	Duty cycle for Gigabit	45	55	%
Duty_T ⁴	Duty cycle for 10/100T	40	60	%
Tr/Tf	Rise/fall time (20–80%)	—	0.75	ns

¹ The timings assume the following configuration:

DDR_SEL = (11)b

DSE (drive-strength) = (111)b

² For 10 Mbps and 100 Mbps, T_{cyc} will scale to 400 ns \pm 40 ns and 40 ns \pm 4 ns respectively.

³ For all versions of RGMII prior to 2.0; this implies that PC board design will require clocks to be routed such that an additional trace delay of greater than 1.5 ns and less than 2.0 ns will be added to the associated clock signal. For 10/100, the Max value is unspecified.

⁴ Duty cycle may be stretched/shrunk during speed changes or while transitioning to a received packet's clock domain as long as minimum duty cycle is not violated and stretching occurs for no more than three T_{cyc} of the lowest speed transitioned between.

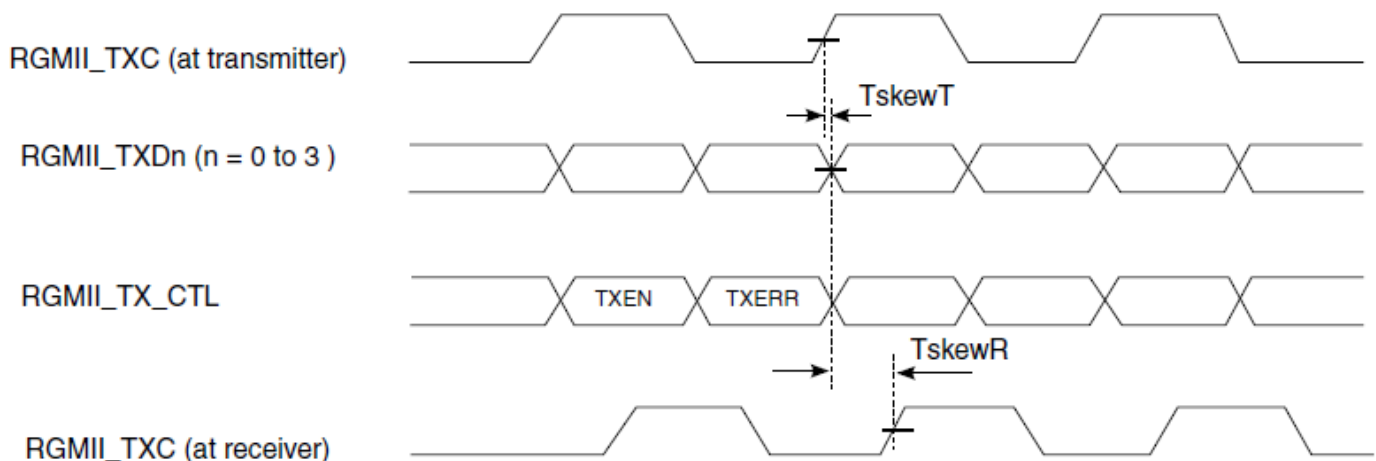


Figure 6. RGMII transmit signal timing diagram original

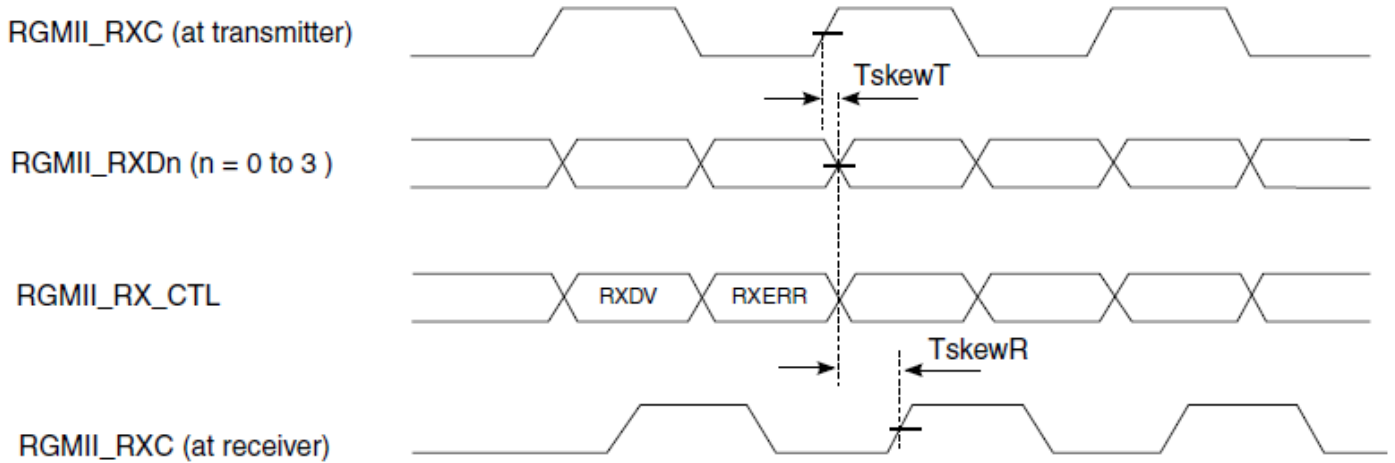


Figure 7. RGMII receive signal timing diagram original

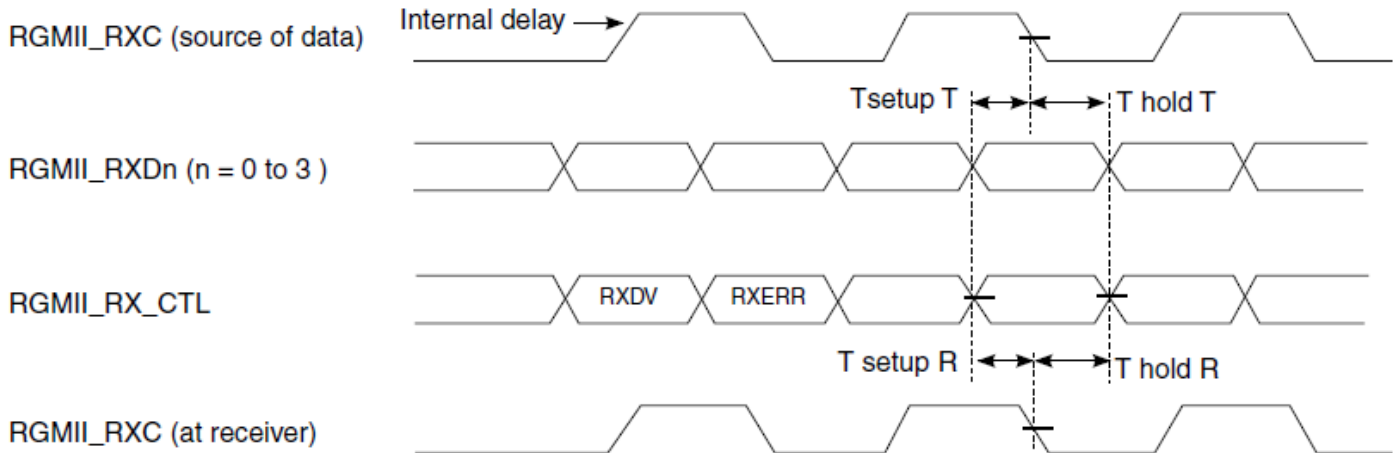


Figure 8. RGMII receive signal timing diagram with internal delay

3.4.4 I2C bus characteristics

The Inter-Integrated Circuit (I2C) provides functionality of a standard I2C master and slave. The I2C is designed to be compatible with the I2C Bus Specification, version 2.1, by Philips Semiconductor (now NXP Semiconductors).

3.4.5 MIPI D-PHY timing parameters

MIPI D-PHY electrical specifications are compliance.

3.4.6 PDM timing parameters

Figure 9 illustrates the input timing of the PDM.

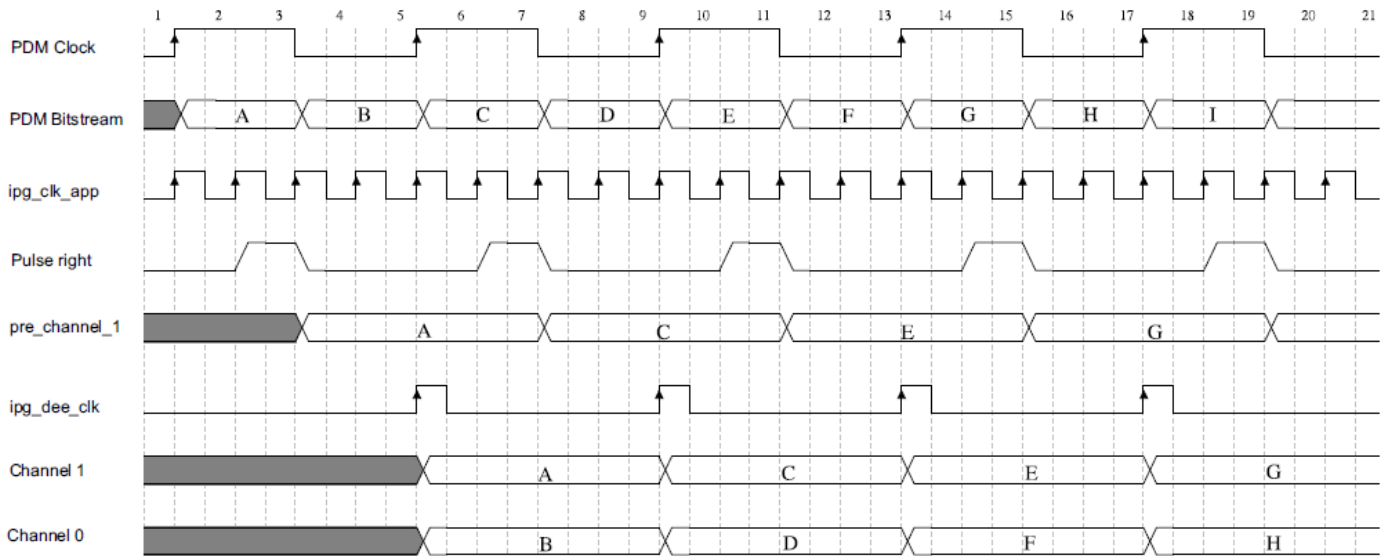


Figure 9. PDM input timing

PDM clock operative range is from 500 kHz to 6 MHz. Within range, only need to configure ipg_clk_app rate and CLKDIV without I/O timing concerns.

3.4.7 SAI/I2S switching specifications

This section provides the AC timings for the SAI in Master (clocks driven) and Slave (clocks input) modes. All timings are given for non inverted serial clock polarity (SAI_TCR[TSCCKP] = 0, SAI_RCR[RSCKP]= 0) and non inverted frame sync (SAI_TCR[TFSI] = 0, SAI_RCR[RFSI] = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timings remain valid by inverting the clock signal (SAI_BCLK) and/or the frame sync (SAI_FS) shown in the figures below.

Table 17. Master mode SAI timing (50 MHz)¹

Num	Characteristic	Min	Max	Unit
S1	SAI_MCLK cycle time	20	—	ns
S2	SAI_MCLK pulse width high/low	40%	60%	MCLK period
S3	SAI_BCLK cycle time	20	—	ns
S4	SAI_BCLK pulse width high/low	40%	60%	BCLK period
S5	SAI_BCLK to SAI_FS output valid	—	2	ns
S6	SAI_BCLK to SAI_FS output invalid	0	—	ns
S7	SAI_BCLK to SAI_TXD valid	—	2	ns
S8	SAI_BCLK to SAI_TXD invalid	0	—	ns
S9	SAI_RXD/SAI_FS input setup before SAI_BCLK	2	—	ns
S10	SAI_RXD/SAI_FS input hold after SAI_BCLK	0	—	ns

¹ To achieve 50 MHz for BCLK operation, clock must be set in feedback mode.

Table 18. Master mode SAI timing (25 MHz)

Num	Characteristic	Min	Max	Unit
S1	SAI_MCLK cycle time	40	—	ns
S2	SAI_MCLK pulse width high/low	40%	60%	MCLK period
S3	SAI_BCLK cycle time	40	—	ns
S4	SAI_BCLK pulse width high/low	40%	60%	BCLK period
S5	SAI_BCLK to SAI_FS output valid	—	2	ns
S6	SAI_BCLK to SAI_FS output invalid	0	—	ns
S7	SAI_BCLK to SAI_TXD valid	—	2	ns
S8	SAI_BCLK to SAI_TXD invalid	0	—	ns
S9	SAI_RXD/SAI_FS input setup before SAI_BCLK	12	—	ns
S10	SAI_RXD/SAI_FS input hold after SAI_BCLK	0	—	ns

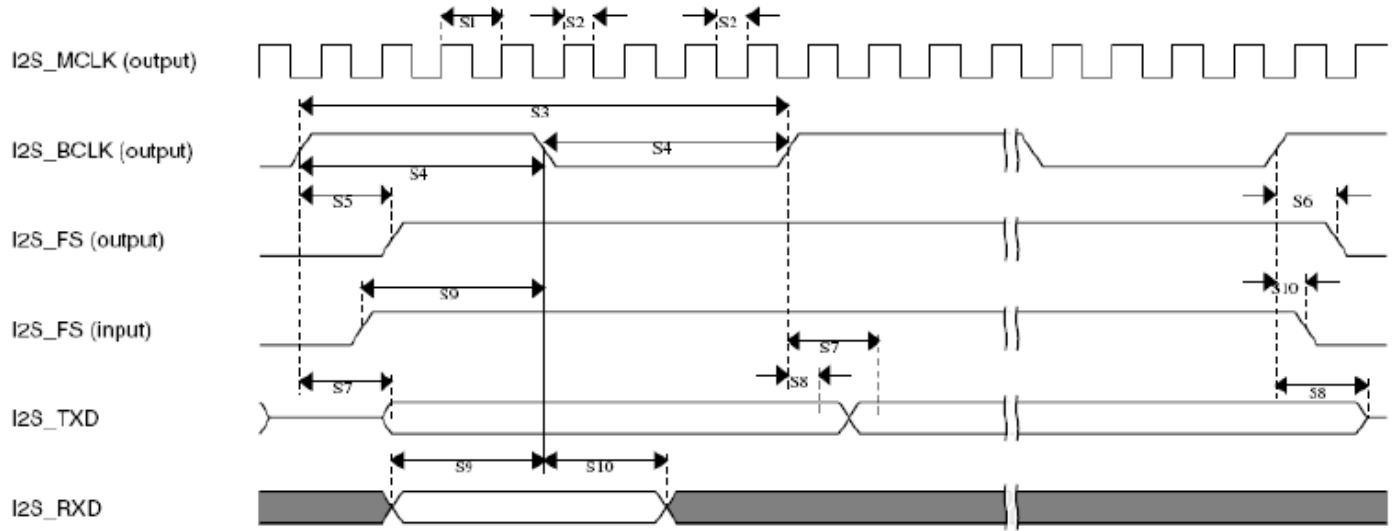


Figure 10. SAI timing—Master modes

Table 19. Slave mode SAI timing (50 MHz)¹

Num	Characteristic	Min	Max	Unit
S11	SAI_BCLK cycle time (input)	20	—	ns
S12	SAI_BCLK pulse width high/low (input)	40%	60%	BCLK period
S13	SAI_FS input setup before SAI_BCLK	2	—	ns
S14	SAI_FA input hold after SAI_BCLK	2	—	ns
S17	SAI_RXD setup before SAI_BCLK	2	—	ns
S18	SAI_RXD hold after SAI_BCLK	2	—	ns

¹ TX does not support 50 MHz operation in Slave mode.

Table 20. Slave mode SAI timing (25 MHz)

Num	Characteristic	Min	Max	Unit
S11	SAI_BCLK cycle time (input)	40	—	ns
S12	SAI_BCLK pulse width high/low (input)	40%	60%	BCLK period
S13	SAI_FS input setup before SAI_BCLK	12	—	ns
S14	SAI_FA input hold after SAI_BCLK	2	—	ns
S15	SAI_BCLK to SAI_TXD/SAI_FS output valid	—	7	ns
S16	SAI_BCLK to SAI_TXD/SAI_FS output invalid	0	—	ns
S17	SAI_RXD setup before SAI_BCLK	12	—	ns
S18	SAI_RXD hold after SAI_BCLK	2	—	ns

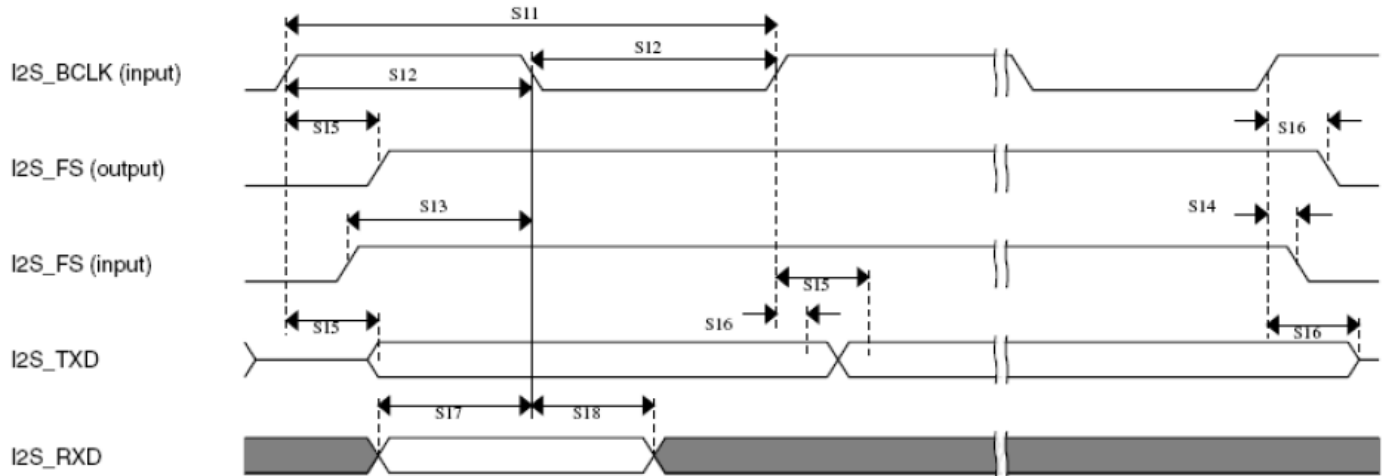


Figure 11. SAI Timing — Slave Modes

3.4.8 SPDIF timing parameters

The Sony/Philips Digital Interconnect Format (SPDIF) data is sent using the bi-phase marking code. When encoding, the SPDIF data signal is modulated by a clock that is twice the bit rate of the data signal. Table 21 and Figure 12 and Figure 13 show SPDIF timing parameters for the Sony/Philips Digital Interconnect Format (SPDIF), including the timing of the modulating Rx clock (SPDIF_SR_CLK) for SPDIF in Rx mode and the timing of the modulating Tx clock (SPDIF_ST_CLK) for SPDIF in Tx mode.

Table 21. SPDIF timing parameters

Parameter	Symbol	Timing Parameter Range		Unit
		Min	Max	
SPDIF_IN Skew: asynchronous inputs, no specs apply	—	—	0.7	ns
SPDIF_OUT output (Load = 50 pf)	—	—	1.5	ns
• Skew	—	—	24.2	
• Transition rising	—	—	31.3	
SPDIF_OUT output (Load = 30 pf)	—	—	1.5	ns
• Skew	—	—	13.6	
• Transition rising	—	—	18.0	
Modulating Rx clock (SPDIF_SR_CLK) period	srckp	40.0	—	ns
SPDIF_SR_CLK high period	srckph	16.0	—	ns
SPDIF_SR_CLK low period	srckpl	16.0	—	ns
Modulating Tx clock (SPDIF_ST_CLK) period	stckp	40.0	—	ns
SPDIF_ST_CLK high period	stckph	16.0	—	ns
SPDIF_ST_CLK low period	stckpl	16.0	—	ns

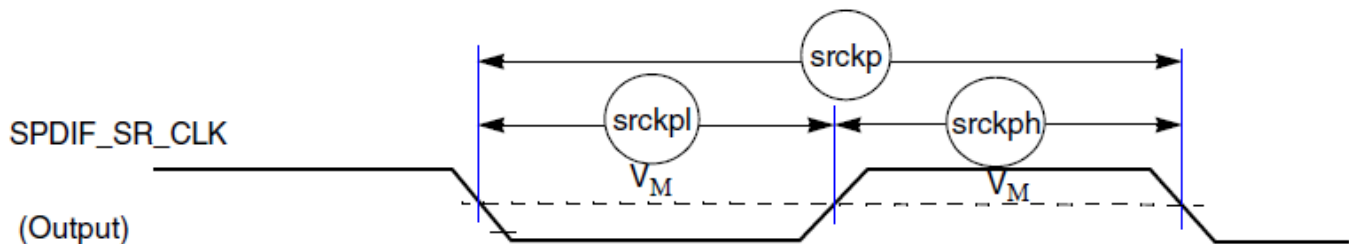


Figure 12. SPDIF_SR_CLK timing diagram

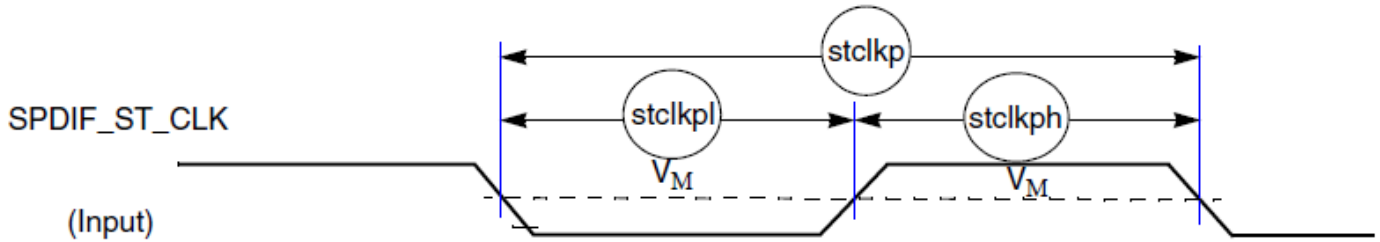


Figure 13. SPDIF_ST_CLK timing diagram

3.4.9 UART I/O configuration and timing parameters

The i.MX 8M Nano UART interfaces can serve both as DTE or DCE device. This can be configured by the DCEDTE control bit (default 0—DCE mode). Table 22 shows the UART I/O configuration based on the enabled mode.

Table 22. UART I/O configuration vs. mode Port

Port	DTE Mode		DCE Mode	
	Direction	Description	Direction	Description
UARTx_RTS_B	Output	UARTx_RTS_B from DTE to DCE	Input	UARTx_RTS_B from DTE to DCE
UARTx_CTS_B	Input	UARTx_CTS_B from DCE to DTE	Output	UARTx_CTS_B from DCE to DTE
UARTx_TX_DATA	Input	Serial data from DCE to DTE	Output	Serial data from DCE to DTE
UARTx_RX_DATA	Output	Serial data from DTE to DCE	Input	Serial data from DTE to DCE

3.4.9.1 UART transmitter

Figure 14 depicts the transmit timing of UART in the RS-232 Serial mode, with 8 data bit/1 stop bit format. Table 23 lists the UART RS-232 Serial mode transmit timing characteristics.

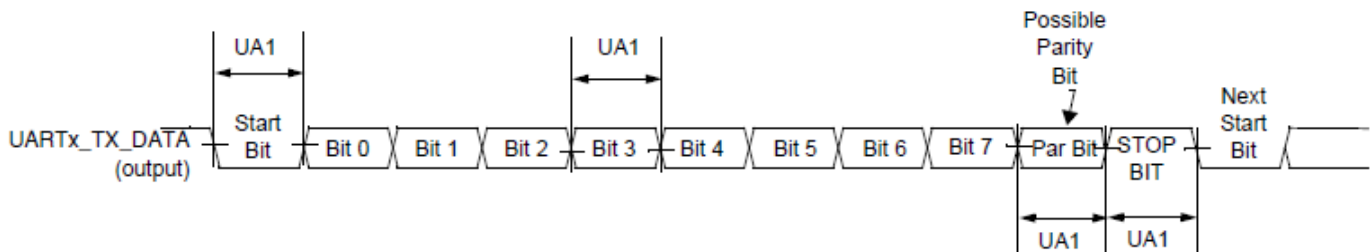


Figure 14. UART RS-232 Serial mode transmit timing diagram

Table 23. RS-232 Serial mode transmit timing parameters

ID	Parameter	Symbol	Min	Max	Unit
UA1	Transmit Bit Time	t_{Tbit}	$1/F_{baud_rate}^1 - T_{ref_clk}^2$	$1/F_{baud_rate} + T_{ref_clk}$	—

¹ F_{baud_rate} : Baud rate frequency. The maximum baud rate the UART can support is $(ipg_perclk \text{ frequency})/16$.

² T_{ref_clk} : The period of UART reference clock ref_clk (ipg_perclk after RFDIV divider).

3.4.9.2 UART receiver

Figure 15 depicts the RS-232 Serial mode receive timing with 8 data bit/1 stop bit format. Table 24 lists Serial mode receive timing characteristics.

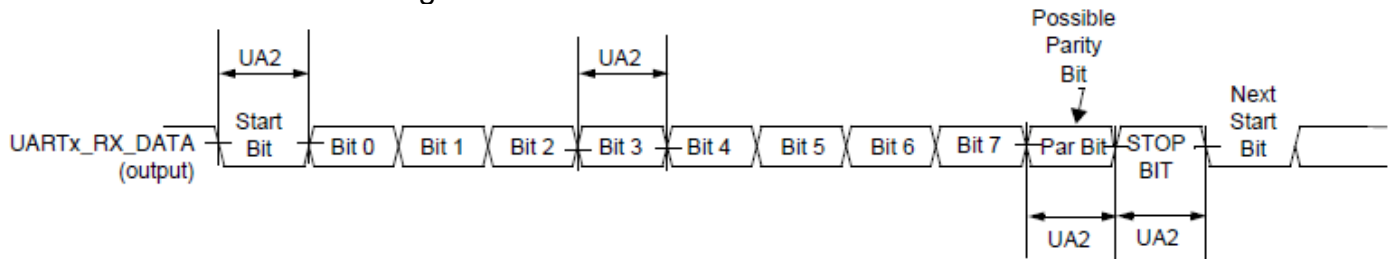


Figure 15. UART RS-232 Serial mode receive timing diagram

Table 24. RS-232 Serial mode receive timing parameters

ID	Parameter	Symbol	Min	Max	Unit
UA2	Receive Bit Time ¹	t_{Rbit}	$1/F_{baud_rate}^2 - 1/(16 \times F_{baud_rate})$	$1/F_{baud_rate} + 1/(16 \times F_{baud_rate})$	—

¹ The UART receiver can tolerate $1/(16 \times F_{baud_rate})$ tolerance in each bit. But accumulation tolerance in one frame must not exceed $3/(16 \times F_{baud_rate})$.

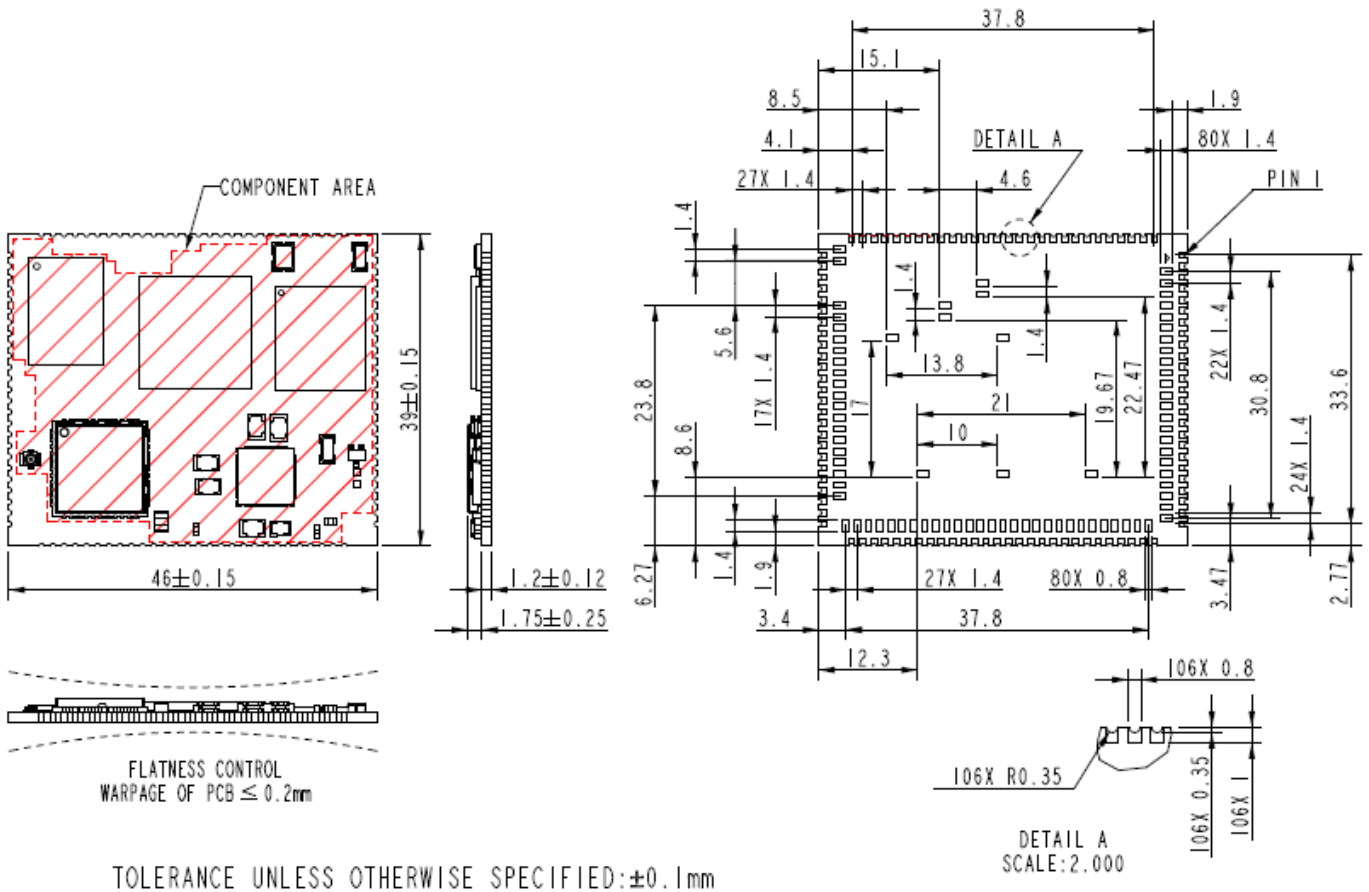
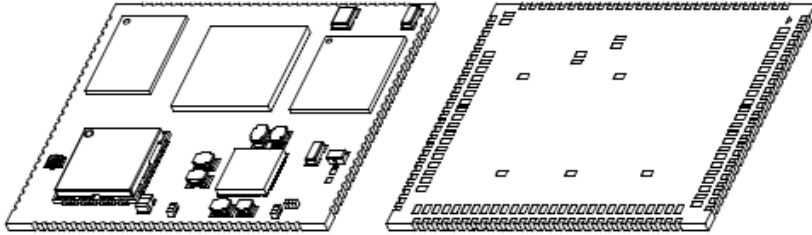
² F_{baud_rate} : Baud rate frequency. The maximum baud rate the UART can support is $(ipg_perclk \text{ frequency})/16$.

3.5 Power Consumption*

Operation mode	Max.	Avg.	remark
Off Mode	211.4 uA	204.2 uA	
Suspend mode with Cortex-M7 enable	17.8 mA	17.4 mA	
IDLE_DEFAULT	151.7 mA	112.5 mA	
IDLE_DEFAULT+WLAN Power Save Mode	162.2 mA	113.1 mA	
Audio Playback+WLAN_2.4G	416.1 mA	164.5 mA	iperf 1Mbit/s over WLAN
4-core Dhryst + WLAN_5G	540.9 mA	480.1 mA	iperf Tx 50Mbit/s

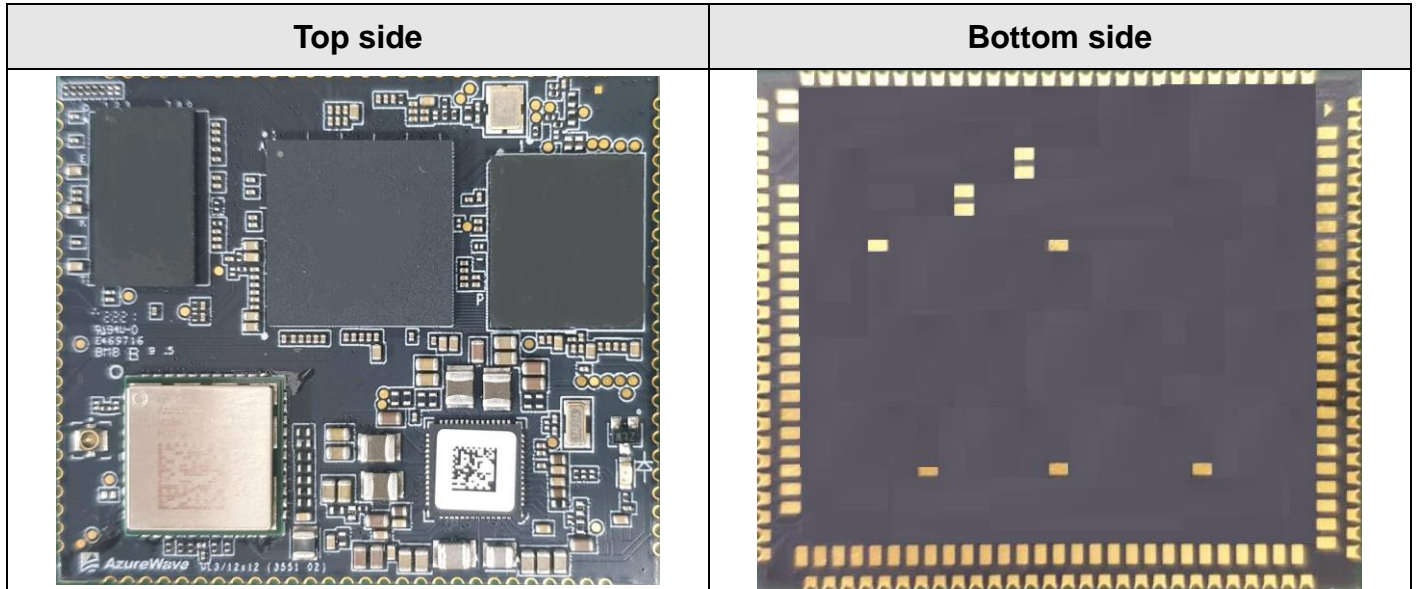
4. Mechanical Information

4.1 Mechanical Drawing



BOT View

4.2 Sample Information



5. 5. Packaging Information

120pcs / box, 720pcs / carton

1. Put 12pcs in one tray, 10 trays in one inner box, and placed an empty tray on the top as the lid, and then tied with two rubber bands.



2. Seal the trays in an aluminum foil bag and put it in the inner box.



3. Put packed product into carton. One package label pasted in side of inner box, six inner boxes inside in one carton.



4. Seal the outside box by AzureWave tape.

